

What is claimed is:

1. An ultraviolet irradiating method for emitting ultraviolet light toward a work piece and a frame holding said work
5 piece through an ultraviolet sensitive adhesive tape applied to a back surface of the work piece, said method comprising:
a step of emitting ultraviolet light to said work piece while supporting an undersurface of said work piece held by said frame in time of ultraviolet irradiation of said work
10 piece.
2. An ultraviolet irradiating method as defined in claim 1, wherein said frame is a ring-shaped frame having an inside diameter of at least 300mm.
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3. An ultraviolet irradiating method as defined in claim 1, wherein said work piece is a semiconductor wafer, glass component or semiconductor package substrate.
- 20 4. An ultraviolet irradiating apparatus for emitting ultraviolet light toward a work piece and a ring-shaped frame holding said work piece through an ultraviolet sensitive adhesive tape applied to a back surface of the work piece, said apparatus comprising:
25 regulating means for limiting a downward displace-

ment of said work piece held by said ring-shaped frame in time of ultraviolet irradiation of said work piece.

5 5. An ultraviolet irradiating apparatus as defined in claim 4, wherein a distance from an undersurface of said work piece to said regulating means is set to at most 3mm.

10 6. An ultraviolet irradiating apparatus as defined in claim 4, wherein said regulating means is formed of glass plate.

7. An ultraviolet irradiating apparatus as defined in claim 6, wherein said glass plate comprises soda glass or tempax glass.

15 8. An ultraviolet irradiating apparatus as defined in claim 7, wherein said glass plate has a thickness of at least 100 μ m.

20 9. An ultraviolet irradiating apparatus as defined in claim 4, wherein said regulating means is formed of a plastic penetrable by ultraviolet light.

10. An ultraviolet irradiating apparatus as defined in claim 9, wherein said plastic is a polyester film or polyester sheet.

25 11. An ultraviolet irradiating apparatus as defined in claim

10, wherein said polyester film or polyester sheet has a thickness of at least 150 μ m.

12. An ultraviolet irradiating apparatus as defined in claim
5 4, wherein said regulating means is formed of metal wires arranged in a grid.

13. An ultraviolet irradiating apparatus as defined in claim
12, wherein said metal wires arranged in a grid have a
10 thickness of at most 0.5mm, and have intervals therebetween of at most 20mm.

14. An ultraviolet irradiating apparatus as defined in claim
4, wherein said regulating means is formed of a cold filter.
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15. An ultraviolet irradiating apparatus as defined in claim
4, wherein said work piece is a semiconductor wafer, glass component or semiconductor package substrate.